

Pb Free Plating Product

2P4M





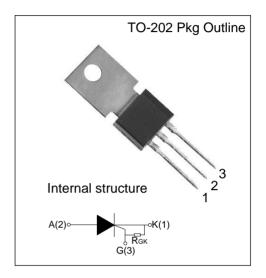
2.0 Ampere Passivated Process Thyristor---Sensitive Gate SCR

DESCRIPTION:

ThinkiSemi 2P4M SCR with the parallel resistor between Gate and Cathode are especially recommended for use on straight hair, igniter, anion generator etc..

MAIN FEATURES

Symbol	Value	Unit	
I _{T(RMS)}	2	А	
I _{GT}	≤200	μΑ	
V _{TM}	≤1.5	V	



ABSOLUTE MAXIMUM RATINGS

Parameter		Symbol	Value	Unit
Storage junction temperature range		T _{stg}	-40-150	$^{\circ}\!\mathbb{C}$
Operating junction temperature range		Tj	-40-110	${\mathbb C}$
Repetitive peak off-state voltage		V_{DRM}	600	V
Repetitive peak reverse voltage		V_{RRM}	600	V
RMS on-state current	@ (T _C =72°C)	I _{T(RMS)}	2	А
Non repetitive surge peak on-state current (tp=10ms)		I _{TSM}	20	А
I ² t value for fusing (tp=10ms)		l ² t	2	A ² s
Critical rate of rise of on-state current		dI/dt	50	A/µs
Peak gate current (tp=20µs, Tj=110°C)		I _{GM}	0.2	Α
Peak gate power (tp=20µs, Tj=110℃)		P_{GM}	0.5	W
Average gate power dissipation(T _j =110℃)		P _{G(AV)}	0.1	W

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ELECTRICAL CHARACTERISTICS (T_j =25 $^{\circ}$ C unless otherwise specified)

Symbol	Test Condition	Value			I Init
Symbol		MIN.	TYP.	MAX.	Unit
I _{GT}	$V_D=12V R_I=33\Omega$	-	40	200	μΑ
V _{GT}	V _D =12V K _L =33Ω	-	0.5	0.8	V
V_{GD}	$V_D=V_{DRM} T_j=110 ^{\circ}C$	0.2	-	-	V
IL	I _G =1.2 I _{GT}	-	-	3	mA
I _H	I _T =0.05A	-	-	2	mA
dV/dt	$V_D=60\%V_{DRM} T_j=110^{\circ}C R_{GK}=1K\Omega$	10	-	-	V/µs

STATIC CHARACTERISTICS

Symbol	Parameter		Value(MAX)	Unit
V_{TM}	I _{TM} =4A tp=380μs	T _j =25℃	1.5	V
I _{DRM}	$V_D = V_{DRM} V_R = V_{RRM}$	T _j =25℃	5	μA
I _{RRM}		T _j =110℃	100	μA

THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
R _{th(j-c)}	junction to case	TO-202 Heat sink	10	°C/W



FIG.1 Maximum power dissipation versus RMS on-state current

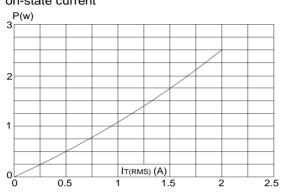


FIG.3: Surge peak on-state current versus number of cycles

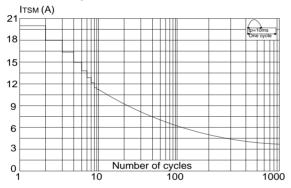


FIG.5: Non-repetitive surge peak on-state current for a sinusoidal pulse with width tp<10ms, and corresponging value of l^2t (dl/dt < 50A/ μ s)

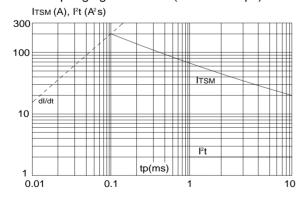


FIG.2: RMS on-state current versus case temperature

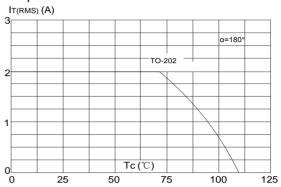


FIG.4: On-state characteristics (maximum values)

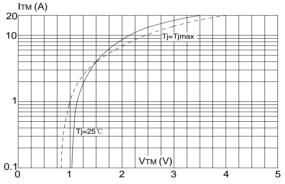
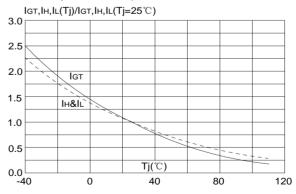


FIG.6: Relative variations of gate trigger current, holding current and latching current versus junction temperature



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